

Now Available!

The Worldwide Electronics IC, PCB & Box Assembly Application Markets - 2011 Edition

***A Unique Database of the Semiconductor and Manufacturing Assembly
Value for 46 Unique Products Applications, Forecasted from 2010 - 2015***

Database Highlights - Published February, 2011

- **Product Segment Analysis, 2010**
 - ◇ **Automotive**
 - ◇ **Communications**
 - ◇ **Computer/Peripherals**
 - ◇ **Consumer Electronics**
 - ◇ **Industrial**
 - ◇ **Medical**
 - ◇ **Aerospace/Military/Other Transportation**

- **Revenue Level Analysis, 2010 - 2015**
 - ◇ **Semiconductor Units, ICs per Unit, Total ICs, ICs Value per Unit, IC Revenue, IC ASPs, Passives/Discretes/ Non-IC Assembly Value**
 - ◇ **PCB and Box Assembly Value**
 - ◇ **Total Assembly Value (COGS)**
 - ◇ **IC/Non-IC/PCB/Box Assembly Value Percentages**

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The Worldwide Electronics IC, PCB & Box Assembly Application Markets

Synopsis

The worldwide electronics manufacturing assembly market continued to recover significantly in 2010. After a painful downturn, the market experienced significant growth in semiconductor sales and assembly value (COGS - cost of goods sold). All indications are that this growth will continue into and beyond 2015.

New Venture Research (NVR) has followed the electronics assembly industry for over 20 years with numerous research reports focusing on all the players and product assemblies in the electronics industry. Now, **NVR** is pleased to offer, **The Worldwide Electronics IC, PCB & Box Assembly Application Markets - 2011 Edition**. This unique database provides 2010 global IC electronics and assembly data by its individual components (semiconductor ICs, passives, discretes, labor/overhead (e.g. PCB assembly value), plus box assembly value) for 46 different product applications. This database is supported with a Word file commentary discussion of the growth market trends of the leading products. This database provides the foundation for NVR's other reports in electronics packaging and electronics product assembly by supplier (OEM, EMS, ODM). This report is the foundation by which our other packaging and assembly market reside providing a complete understanding of the cost elements for leading electronics products including IC semiconductor, PCB board and Box assembly cost elements in the leading electronics product assembly application markets.

The database divides the global electronics industry into seven critical market segments including:

Automotive

Communications

Computers /Peripherals

Consumer Electronics

Industrial

Medical

Aerospace/Military/Other Transportation

The following production data are provided for each leading product application area.

Semiconductor ICs (Units, ASPs, Rev.)

Passives/Discretes (Units, ASPs, Rev.)

Non-PCB Assembly (Units, ASPs, Rev.)

PCB Assembly (Units, ASPs, Rev.)

Box Assembly (Units, ASPs, Rev.)

Total Assembly (Units, ASPs, Rev.)

A discussion of each market application and the trends is included with the database in a Word document. Each market segment and individual product application is reviewed for semiconductor, PCB and Box costing trends.

The Worldwide Electronics IC, PCB & Box Assembly Application Markets - 2011 Edition, will provide the critical information

you need on electronics COGS assembly. The Excel and Word files are shipped by email as a single-user license priced at \$2,995. An extra single user license is \$250 and a corporate license is \$1000.

About the Authors

Sandra Winkler, is a senior analyst and has authored all of NVR's widely cited reports on IC packaging. She is a senior member of IEEE/CPMT, serves on the executive committee for the IEEE-CPMT-SCV chapter and holds a MBA from Santa Clara University. **Randall Sherman**, president of New Venture Research Corp. and serves as principal analyst for this database. Mr. Sherman has more than 25 years' experience in technology and business research. He holds a B.S. degree in astrophysics, a MSEE from the University of Colorado, and a MBA from Edinburgh School of Business.

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Database Tables including - Units (M), ASP (\$), Rev. (\$M)

Segment 1: Automotive

Automotive Engine Controls
Automotive Instruments
Automotive Safety
Automotive Entertainment
Total Automotive
Automotive OEM Summary (Word file)
(Total ICs, passives/discretes, labor/overhead
(e.g. PCB assembly value) & box assembly)

Segment 2: Communications

Mobile Phones (smart and dumb)
Mobile Phone Infrastructure
Other Phones (cordless 7 standard)
Enterprise LANs
Wireless LANs
DSL/Cable Modems
PBX/Key Systems
Carrier-Class Equipment
Other Communications (satellite, etc.)
Total Communications
Communications OEM Summary (Word file)
(Total ICs, passives/discretes, labor/overhead
(e.g. PCB assembly value) & box assembly)

Segment 3: Computer/Peripherals

Notebooks
Desktops
Tablets
Servers
Workstations
ESS
Monitors
Printers
E-Readers
Other Computer
Total Computer
Computer OEM Summary (Word file)
(Total ICs, passives/discretes, labor/overhead
(e.g. PCB assembly value) & box assembly)

Segment 4: Consumer Electronics

Analog TV
Digital TV MP3
Other Audio
Video Console Games

Set-Top Boxes
Camcorders
DVD/DVRs
Digital Cameras
Personal Navigation
Other Consumer (Appliances)
Total Consumer
Consumer OEM Summary (Word file)
(Total ICs, passives/discretes, labor/overhead
(e.g. PCB assembly value) & box assembly)

Segment 5: Industrial

Process Control
Test & Measurement
Other Industrial
Total Industrial
Total Industrial OEM Summary (Word file)
(Total ICs, passives/discretes, labor/overhead
(e.g. PCB assembly value) & box assembly)

Segment 6: Medical

Monitoring
Therapeutic
Diagnostics/Surgical
Total Medical
Medical OEM Summary (Word file)
(Total ICs, passives/discretes, labor/overhead
(e.g. PCB assembly value) & box assembly)

Segment 7: Aerospace/Military/Other Transportation

In-Flight Entertainment
Navigation Systems
Weapons
C3 Systems
Other Military
Other Aerospace/Other Transportation
Total Aerospace/Other Transportation
Aerospace/Other OEM Summary (Word file)
(Total ICs, passives/discretes, labor/overhead
(e.g. PCB assembly value) & box assembly)

Each product segment contains revenue, unit and ASP product-level information for ICs, PCB and Box Assembly COGS.

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Sample Summary Database Table for Computer/Peripherals Products

<u>Computer/Peripherals</u>	<u>2010</u>	<u>2011</u>	<u>2012</u>	<u>2013</u>	<u>2014</u>	<u>2015</u>	<u>CAGR</u>
Product Units (M)	XXX	XXX	XXX	XXX	XXX	XXX	12.7%
Total ICs (M)	XXXX	XXXX	XXXX	XXXX	XXXX	XXXX	15.9%
IC\$ Per Unit	\$\$\$	\$\$\$	\$\$\$	\$\$\$	\$\$\$	\$\$\$	6.9%
IC Rev (\$M)	\$\$\$\$	\$\$\$\$	\$\$\$\$	\$\$\$\$	\$\$\$\$	\$\$\$\$	13.1%
ICs Per Unit (M)	XX	XX	XX	XX	XX	XX	5.5%
ICs (M)	XXXX	XXXX	XXXX	XXXX	XXXX	XXXX	15.3%
PCB Assy--IC Value Per Unit (\$)	\$\$\$	\$\$\$	\$\$\$	\$\$\$	\$\$\$	\$\$\$	12.8%
PCB Assy--IC Value (\$)	\$\$	\$\$	\$\$	\$\$	\$\$	\$\$	12.7%
PCB Assy--Non-IC Value Per Unit (\$)	\$\$\$	\$\$\$	\$\$\$	\$\$\$	\$\$\$	\$\$\$	11.8%
PCB Assy--Non-IC Value (\$)	\$\$	\$\$	\$\$	\$\$	\$\$	\$\$	11.7%
PCB Assy Value (\$M)	\$\$\$\$	\$\$\$\$	\$\$\$\$	\$\$\$\$	\$\$\$\$	\$\$\$\$	13.3%
PCB Assy % of Total Assy	XX.X%	XX.X%	XX.X%	XX.X%	XX.X%	XX.X%	N/A
Box Assy Value Per Unit (\$)	\$\$	\$\$	\$\$	\$\$	\$\$	\$\$	11.7%
Box Assy Value (\$M)	\$\$\$	\$\$\$	\$\$\$	\$\$\$	\$\$\$	\$\$\$	11.6%
Total Assy Value (\$M)	\$\$\$\$\$	\$\$\$\$\$	\$\$\$\$\$	\$\$\$\$\$	\$\$\$\$\$	\$\$\$\$\$	13.2%
% of Total Assy Value	XX.X%	XX.X%	XX.X%	XX.X%	XX.X%	XX.X%	N/A
Box Assy/Total Assy Value	XX.X%	XX.X%	XX.X%	XX.X%	XX.X%	XX.X%	N/A
Total Assy Value Per Unit (\$)	\$\$\$	\$\$\$	\$\$\$	\$\$\$	\$\$\$	\$\$\$	12%
PCB Assy--Non-IC Value (%)	XX.X%	XX.X%	XX.X%	XX.X%	XX.X%	XX.X%	N/A
PCB Assy--Non-IC Value (\$)	\$\$\$	\$\$\$	\$\$\$	\$\$\$	\$\$\$	\$\$\$	10.8%

Published Feb., 2011 - Excel Database (7 vertical market segments) & Word file discussion (43 pages)

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The Worldwide Electronics IC, PCB & Box Assembly Application Markets - 2011 Edition (2010 database)

\$2,995

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Returns: No return privileges. **International Orders:** Must be prepaid, please contact us for payment arrangements.

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TOTAL